

Mag Layers USA, INC

Specification Sheet

P/N: MSCDRI-8D43-Series-RU-RU

Products:

Certifications:

Molded Power Chokes

Multilayer Chip Inductors

Lan Transformer

RF Passive / Antennas

<u>Automotive</u>

<u>ISO9001</u>

IATF16949

<u>ISO14001</u>

QC080000

US Office

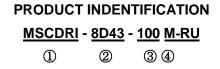
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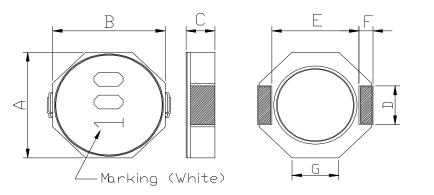
SCOPE :

This specification applies to the Pb Free high current type SMD inductors for MSCDRI-8D43-SERIES



- ① Product Code
- ② Dimensions Code
- ③ Inductance Code
- ④ Tolerance Code

(1) SHAPES AND DIMENSIONS



A: 8.00±0.3 mm B: 8.00±0.3 mm C: 4.50 Max mm D: 2.50 Typ. mm E: 6.30 Typ. mm F: 1.20 Typ. mm G: 3.30 Typ. mm

(2) ELECTRICAL SPECIFICATIONS SEE TABLE 1

TEST INSTRUMENTS

L : HP 4284A PRECISION LCR METER (or equivalent)

RDC : CHROMA MODEL 16502 MILLIOHMMETER (or equivalent)

(3) CHARACTERISTICS

- (3)-1 Ambient temperature +60 $^\circ\!\!\! C$ Max.
- (3)-2 Operate temperature range -40° C \sim $+125^{\circ}$ C
 - (Including self temp. rise)
- (3)-3 Storage temperature range $-40^\circ\!\!\mathbb{C}\,{\sim}\,{+}\,125^\circ\!\!\mathbb{C}$



MSCDRI-8D43-SERIES-RU

MAGLAYERS	Inductance	Percent	Test	Resistance	Rated DC Current		
							Marking
PT/NO.	L(µH)	Tolerance	Frequency	RDC(Ω) Max.	IDC1(A)	IDC2(A)	
MSCDRI-8D43-1R0 RU	1.0	N	100kHz/0.25V	12.2m	8.00	6.20	1R0
MSCDRI-8D43-1R2 RU	1.2	Ν	100kHz/0.25V	12.2m	8.00	6.20	1R2
MSCDRI-8D43-2R0 -RU	2.0	Ν	100kHz/0.25V	14m	7.00	5.50	2R0
MSCDRI-8D43-2R2 RU	2.2	Ν	100kHz/0.25V	16m	6.80	5.00	2R2
MSCDRI-8D43-3R6 -RU	3.6	M,N	100kHz/0.25V	19m	5.90	4.50	3R6
MSCDRI-8D43-3R9RU	3.9	Ν	100kHz/0.25V	19m	5.90	4.50	3R9
MSCDRI-8D43-4R7 -RU	4.7	M,N	100kHz/0.25V	22m	5.60	4.10	4R7
MSCDRI-8D43-6R8□-RU	6.8	M,N	100kHz/0.25V	25m	4.40	3.90	6R8
MSCDRI-8D43-8R2 -RU	8.2	M,N	100kHz/0.25V	33m	4.20	3.60	8R2
MSCDRI-8D43-100 RU	10	M,N	100kHz/0.25V	36m	4.00	3.20	100
MSCDRI-8D43-150 -RU	15	M,N	100kHz/0.25V	62m	2.90	2.30	150
MSCDRI-8D43-220 RU	22	M,N	100kHz/0.25V	75m	2.60	1.80	220
MSCDRI-8D43-330 -RU	33	M,N	100kHz/0.25V	0.125	2.20	1.14	330
MSCDRI-8D43-470 RU	47	M,N	100kHz/0.25V	0.150	1.80	1.30	470
MSCDRI-8D43-680 RU	68	M,N	100kHz/0.25V	0.240	1.50	1.00	680
MSCDRI-8D43-101 -RU	100	M,N	100kHz/0.25V	0.360	1.30	0.80	101
MSCDRI-8D43-121 -RU	120	M,N	100kHz/0.25V	0.510	1.00	0.70	121

TABLE 1

※ □ specify the inductance tolerance,M(±20%),N(±30%)

M IDC1 : Based on inductance change (\triangle L/Lo : drop 35% Max.) @Ambient Temperature : 25 $^{\circ}$ C

IDC2 : Based on temperature rise ($\triangle T$: 40°C TYP.)

Rated DC Current : The less value which is IDC1 or IDC2.



(4) RELIABILITY TEST METHOD

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS			
Substrate bending	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board			
		in figure 1 and a load applied unitil the figure in the arrow			
	There shall be	direction is made approximately 3mm.(keep time 30 seconds)			
	no mechanical	PCB dimension shall the page 7/9			
	damage or elec-	F(Pressurization)			
	trical damege.				
		R5 45±2 45±2			
		PRESSURE ROD figure-1			
Vibration	∆L/Lo≦±5%	The sample shall be soldered onto the printed circuit board			
		and when a vibration having an amplitude of 1.52mm			
	There shall be	and a frequency of from 10 to 55Hz/1 minute repeated should			
	no mechanical	be applied to the 3 directions (X,Y,Z) for 2 hours each.			
	damage.	(A total of 6 hours)			
Coldershility	New solder	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated			
Solderability	More than 90%	over the whole of the sample before hard, the sample shall			
		then be preheated for about 2 minutes in a temperature of			
		130 \sim 150 $^\circ\!\mathrm{C}$ and after it has been immersed to a depth 0.5mm			
		below for 3±0.2 seconds fully in molten solder M705 with			
		a temperature of 245±5℃.			
		More than 90% of the electrode sections shall be couered			
		with new solder smoothly when the sample is taken out of			
		the solder bath.			



MECHANICAL

TEST ITEM	SPECIFICATION					
Resistance to Soldering heat	There shall be no damage or problems.	SPECIFICATION Temperature profile of reflow soldering Soldering (Peak temperature 260±3℃ 10 sec 90 200 Pre-heating Slow cooling Slow cooling				
		The specimen shall be passed through the reflow condition shown in the above profile for 1 time.				

ELECTRICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Insulation	There shall be	DC 100V voltage shall be applied across this sample of top
resistance	no other	surface and the terminal.
	damage or	The insulation resistance shall be more than $1 \times 10^8 \Omega$.
	problems.	
Dielectric	There shall be	AC 100V voltage shall be applied for 1 minute acrosset the top
withstand	no other	surface and the terminal of this sample
voltage	damage or	
	problems.	
Temperature	∆L/L20℃≦±10%	The test shall be performed after the sample has stabilized in
characteristics	0~2000 ppm/℃	an ambient temperature of -20 to +85 $^\circ\!\mathrm{C}$,and the value
		calculated based on the value applicable in a normal
		temperature and narmal humidity shall be $ riangle L/L20^{\circ}C \leq \pm 10\%$.



ENVIROMENT CHARACTERISTICS

TEST ITEM				SPECIFICATION			
High temperature	∆L/Lo≦±5%	\triangle L/Lo \leq ±5% The sample shall be left for 96±4 hours in an atmospere with					
storage		a tempe	a temperature of 85±2 $^\circ\!\!{ m C}$ and a normal humidity.				
	There shall be	Upon co	Upon completion of the measurement shall be made after the				
	no mechanical	sample	sample has been left in a normal temperature and normal				
	damage.	humidit	humidity for 1 hour.				
Low temperature	∆L/Lo≦±5%	The san	The sample shall be left for 96±4 hours in an atmosphere with				
storage		a tempe	a temperature of -25±3℃.				
	There shall be	Upon co	omplet	tion of the test, the mea	surement shall be mad	е	
	no mechanical	after the	after the sample has been left in a normal temperature and				
	damage.	normal	normal humidity for 1 hour.				
Change of	∆L/Lo≦±5%	The san	nple sl	hall be subject to 5 cont	inuos cycles, such as s	shown	
temperature		in the ta	ble 2	below and then it shall b	be subjected to standar	ď	
	There shall be	atmosp	heric o	conditions for 1 hour, af	ter which measuremen	t	
	no other dama-	shall be	made	.			
	ge of problems						
			r	table 2			
				Temperature	Duration		
			1	− 25±3° C	30 min.		
				(Themostat No.1)			
			2	Standard	No.1→No.2		
				atmospheric			
			3	85±2℃	30 min.		
				(Themostat No.2)			
			4	Standard	No.2→No.1		
				atmospheric			
Moisture storage	∆L/Lo≦±5%	The san	nple sl	hall be left for 96±4 hou	rs in a temperature of		
-		$40\pm2^{\circ}$ and a humidity(RH) of 90~95%.					
	There shall be	Upon completion of the test, the measurement shall be made					
	no mechanical	after the	after the sample has been left in a normal temperature and				
	damage.	normal	normal humidity more than 1 hour.				
Test conditions :	1	U					
The s	sample shall be reflow	w soldered	d onto	the printed circuit boar	d in every test.		

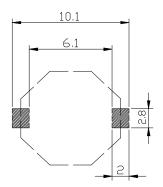


(5) LAND DIMENSION (Ref.)

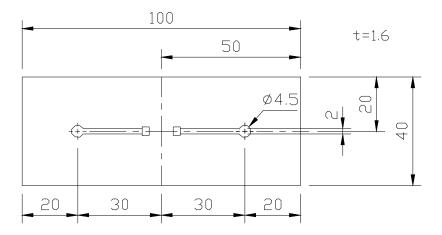
PCB: GLASS EPOXY t=1.6mm

(5)-1 LAND PATTERN DIMENSIONS

(STANDARD PATTERN) Unit : mm

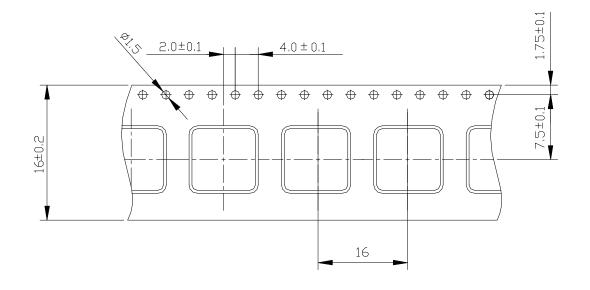


(5)-2 SUBSTRATE BENDING TEST BENDING TEST BOARD

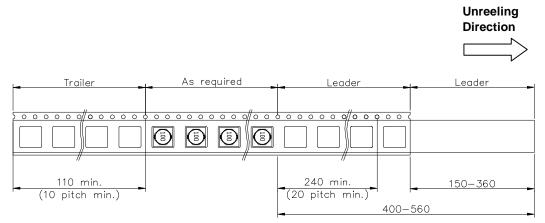




(6) PACKAGING (6)-1 CARRIER TAPE DIMENSIONS (mm)

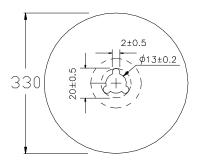


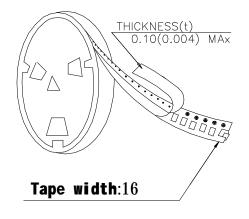
(6)-2 TAPING DIMENSIONS (mm)





(6)-3 REEL DIMENSIONS (mm)





(6)-4 QUANTITY

900pcs/Reel

The products are packaged so that no damage will be sustained.

